PRELIMINARY

Integrated Circuit Systems, Inc.

ICS840004I-01

FEMTOCLOCKS™ CRYSTAL-TO-LVCMOS/LVTTL FREQUENCY SYNTHESIZER

GENERAL DESCRIPTION

The ICS840004I-01 is a 4 output LVCMOS/LVTTL Synthesizer optimized to generate Ethernet reference clock frequencies and is a member of the HiPerClocks™ family of high performance clock solutions from ICS. Using a 25MHz, 18pF parallel resonant crystal, the following frequencies can be generated based on the 2 frequency select pins (F_SEL1:0): 156.25MHz, 125MHz, and 62.5MHz. The ICS840004I-01 uses ICS' 3rd generation low phase noise VCO technology and can achieve 1ps or lower typical random rms phase jitter, easily meeting Ethernet jitter requirements. The ICS840004I-01 is packaged in a small 20-pin TSSOP package.

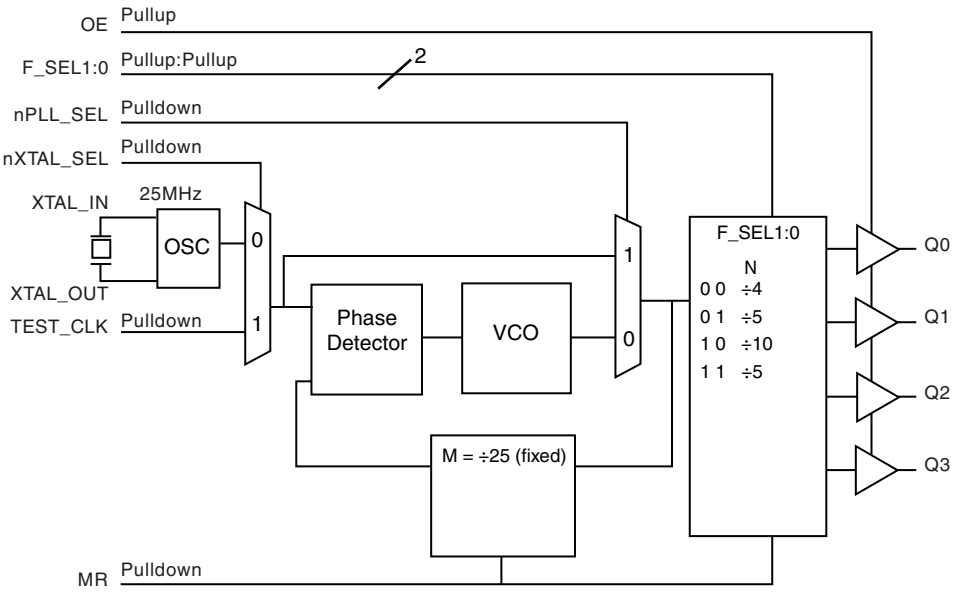
FEATURES

- Four LVCMOS/LVTTL outputs, 15Ω typical output impedance
- Selectable crystal oscillator interface or LVCMOS single-ended input
- Supports the following output frequencies: 156.25MHz, 125MHz and 62.5MHz
- RMS phase jitter @ 156.25MHZ (1.875MHz - 20MHz): 0.52ps (typical)
- Output supply modes:
  Core/Output
  3.3V/3.3V
  3.3V/2.5V
  2.5V/2.5V
- -40°C to 85°C ambient operating temperature

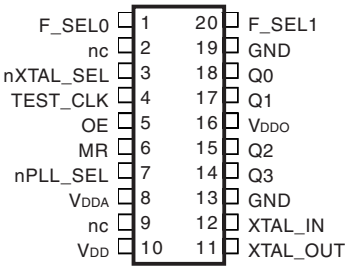
FREQUENCY SELECT FUNCTION TABLE

Inputs					Output Frequency (MHz) (25MHz Ref.)
F_SEL1	F_SEL0	M Divider Value	N Divider Value	M/N Ratio Value	
0	0	25	4	6.25	156.25
0	1	25	5	5	125
1	0	25	10	2.5	62.5
1	1	25	5	5	125

BLOCK DIAGRAM



PIN ASSIGNMENT



ICS840004I-01
20-Lead TSSOP
6.5mm x 4.4mm x 0.92mm
package body
G Package
Top View

The Preliminary Information presented herein represents a product in prototyping or pre-production. The noted characteristics are based on initial product characterization. Integrated Circuit Systems, Incorporated (ICS) reserves the right to change any circuitry or specifications without notice.

TABLE 1. PIN DESCRIPTIONS

Number	Name	Type		Description
1, 20	F_SEL0, F_SEL1	Input	Pullup	Frequency select pin. LVCMOS/LVTTL interface levels.
2, 9	nc	Unused		No connect.
3	nXTAL_SEL	Input	Pulldown	Selects between the crystal or TEST_CLK inputs as the PLL reference source. When HIGH, selects TEST_CLK. When LOW, selects XTAL inpus. LVCMOS/LVTTL interface levels.
4	TEST_CLK	Input	Pulldown	Single-ended LVCMOS/LVTTL clock input.
5	OE	Input	Pullup	Output enable pin. When HIGH, the outputs are active. When LOW, the outputs are in a high impedance state. LVCMOS/LVTTL interface levels.
6	MR	Input	Pulldown	Active HIGH Master Reset. When logic HIGH, the internal dividers are reset causing the otuputs to go low. When logic LOW, the internal dividers and the outputs are enabled. LVCMOS/LVTTL interface levels.
7	nPLL_SEL	Input	Pulldown	PLL Bypass. When LOW, the output is driven from the VCO output. When HIGH, the PLL is bypassed and the output frequency = reference clock frequency/N output divider. LVCMOS/LVTTL interface levels.
8	V_{DDA}	Power		Analog supply pin.
10	V_{DD}	Power		Core supply pin.
11, 12	XTAL_OUT, XTAL_IN	Input		Crystal oscillator interface. XTAL_OUT is the output. XTAL_IN is the input.
13, 19	GND	Power		Power supply ground.
14, 15 17, 18	Q3, Q2, Q1, Q0	Output		Single-ended clock outputs. LVCMOS/LVTTL interface levels. 15Ω typical output impedence.
16	V_{DDO}	Power		Output supply pin.

NOTE: *Pullup* and *Pulldown* refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C_{IN}	Input Capacitance			4		pF
C_{PD}	Power Dissipation Capacitance	V_{DD}, V_{DDA}, V_{DDO} = 3.465V		TBD		pF
		V_{DD}, V_{DDA} = 3.465V, V_{DDO} = 2.625V		TBD		pF
		V_{DD}, V_{DDA}, V_{DDO} = 2.625V		TBD		pF
R_{PULLUP}	Input Pullup Resistor			51		kΩ
$R_{PULLDOWN}$	Input Pulldown Resistor			51		kΩ
R_{OUT}	Output Impedance			15		Ω

ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V_{DD}	4.6V
Inputs, V_I	-0.5V to V_{DD} + 0.5 V
Outputs, V_O	-0.5V to V_{DD} + 0.5V
Package Thermal Impedance, θ_{JA}	73.2°C/W (0 lfpm)
Storage Temperature, T_{STG}	-65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

TABLE 3A. POWER SUPPLY DC CHARACTERISTICS, $V_{DDD} = V_{DDA} = 3.3V±5\%$, $V_{DDO} = 3.3V±5\%$ OR $2.5V±5\%$, T_A = -40°C TO 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{DD}	Core Supply Voltage		3.135	3.3	3.465	V
V_{DDA}	Analog Supply Voltage		3.135	3.3	3.465	V
V_{DDO}	Output Supply Voltage		3.135	3.3	3.465	V
			2.375	2.5	2.625	V
I_{DD}	Power Supply Current			90		mA
I_{DDA}	Analog Supply Current			8		mA
I_{DDO}	Output Supply Current			5		mA

TABLE 3B. POWER SUPPLY DC CHARACTERISTICS, $V_{DD} = V_{DDA} = V_{DDO} = 2.5V±5\%$, T_A = -40°C TO 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{DD}	Core Supply Voltage		2.375	2.5	2.625	V
V_{DDA}	Analog Supply Voltage		2.375	2.5	2.625	V
V_{DDO}	Output Supply Voltage		2.375	2.5	2.625	V
I_{DD}	Power Supply Current			80		mA
I_{DDA}	Analog Supply Current			8		mA
I_{DDO}	Output Supply Current			5		mA

TABLE 3C. LVCMOS/LVTTL DC CHARACTERISTICS, $V_{DD} = V_{DDA} = V_{DDO} = 3.3V±5\%$ OR $2.5V±5\%$, OR $V_{DD} = V_{DDA} = 3.3V±5\%$, $V_{DDO} = 2.5V±5\%$, $T_A = -40°C$ TO $85°C$

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V_{IH}	Input High Voltage		$V_{DD} = 3.3V$	2		$V_{DD} + 0.3$	V
			$V_{DD} = 2.5V$	1.7		$V_{DD} + 0.3$	V
V_{IL}	Input Low Voltage		$V_{DD} = 3.3V$	-0.3		0.8	V
			$V_{DD} = 2.5V$	-0.3		0.7	V
I_{IH}	Input High Current	OE, F_SEL0:1	$V_{DD} = V_{IN} = 3.465V$ or $2.625V$			5	µA
		nPLL_SEL, MR, nXTAL_SEL, TEST_CLK	$V_{DD} = V_{IN} = 3.465V$ or $2.625V$			150	µA
I_{IL}	Input Low Current	OE, F_SEL0:1	$V_{DD} = 3.465V$ or $2.5V$, $V_{IN} = 0V$	-150			µA
		nPLL_SEL, MR, nXTAL_SEL, TEST_CLK	$V_{DD} = 3.465V$ or $2.5V$, $V_{IN} = 0V$	-5			µA
V_{OH}	Output High Voltage; NOTE 1		$V_{DDO} = 3.3V ± 5\%$	2.6			V
			$V_{DDO} = 2.5V ± 5\%$	1.8			V
V_{OL}	Output Low Voltage; NOTE 1		$V_{DDO} = 3.3V$ or $2.5V ± 5\%$			0.5	V

NOTE 1: Outputs terminated with 50Ω to $V_{DDO}/2$. See Parameter Measurement Information, Output Load Test Circuit.

TABLE 4. CRYSTAL CHARACTERISTICS

Parameter	Test Conditions	Minimum	Typical	Maximum	Units
Mode of Oscillation		Fundamental			
Frequency			25		MHz
Equivalent Series Resistance (ESR)				50	Ω
Shunt Capacitance				7	pF
Drive Level				1	mW

NOTE: Characterized using an 18pf parallel resonant crystal.

TABLE 5A. AC CHARACTERISTICS, $V_{DD} = V_{DDA} = V_{DDO} = 3.3V±5\%$, $T_A = -40°C$ TO $85°C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f_{OUT}	Output Frequency			156.25		MHz
				125		MHz
				62.5		MHz
*t*sk(o)	Output Skew; NOTE 1, 2			TBD		ps
*t*jit(Ø)	RMS Phase Jitter (Random); NOTE 3	156.25MHz, (1.875MHz - 20MHz)		0.52		ps
		125MHz, (1.875MHz - 20MHz)		0.65		ps
		62.5MHz, (1.875MHz - 20MHz)		0.55		ps
t_L	PLL Lock Time			TBD		ms
t_R / t_F	Output Rise/Fall Time	20% to 80%		400		ps
odc	Output Duty Cycle			50		%

NOTE 1: Defined as skew between outputs at the same supply voltages and with equal load conditions. Measured at $V_{DDO}/2$.
NOTE 2: This parameter is defined in accordance with JEDEC Standard 65.
NOTE 3: Please refer to the Phase Noise Plot.

TABLE 5B. AC CHARACTERISTICS, $V_{DD} = V_{DDA} = 3.3V±5\%$, $V_{DDO} = 2.5V±5\%$, T_A = -40°C TO 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f_{OUT}	Output Frequency			156.25		MHz
				125		MHz
				62.5		MHz
*t*sk(o)	Output Skew; NOTE 1, 2			TBD		ps
*t*jit(Ø)	RMS Phase Jitter (Random); NOTE 3	156.25MHz, (1.875MHz - 20MHz)		0.48		ps
		125MHz, (1.875MHz - 20MHz)		0.59		ps
		62.5MHz, (1.875MHz - 20MHz)		0.53		ps
t_L	PLL Lock Time			TBD		ms
t_R / t_F	Output Rise/Fall Time	20% to 80%		450		ps
odc	Output Duty Cycle			50		%

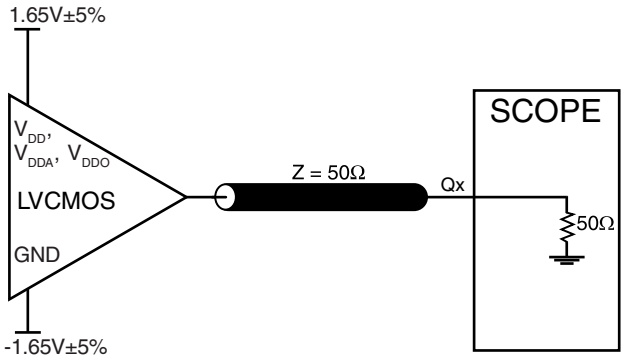
NOTE 1: Defined as skew between outputs at the same supply voltages and with equal load conditions. Measured at $V_{DDO}/2$.
NOTE 2: This parameter is defined in accordance with JEDEC Standard 65.
NOTE 3: Please refer to the Phase Noise Plot.

TABLE 5C. AC CHARACTERISTICS, $V_{DD} = V_{DDA} = V_{DDO} = 2.5V±5\%$, T_A = -40°C TO 85°C

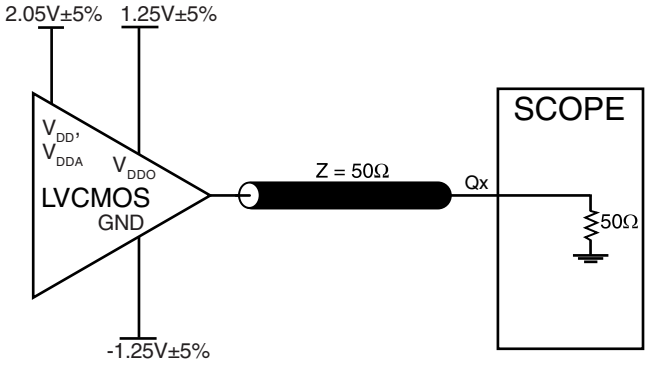
Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f_{OUT}	Output Frequency			156.25		MHz
				125		MHz
				62.5		MHz
*t*sk(o)	Output Skew; NOTE 1, 2			TBD		ps
*t*jit(Ø)	RMS Phase Jitter (Random); NOTE 3	156.25MHz, (1.875MHz - 20MHz)		0.50		ps
		125MHz, (1.875MHz - 20MHz)		0.60		ps
		62.5MHz, (1.875MHz - 20MHz)		0.51		ps
t_L	PLL Lock Time			TBD		ms
t_R / t_F	Output Rise/Fall Time	20% to 80%		450		ps
odc	Output Duty Cycle			50		%

NOTE 1: Defined as skew between outputs at the same supply voltages and with equal load conditions. Measured at $V_{DDO}/2$.
NOTE 2: This parameter is defined in accordance with JEDEC Standard 65.
NOTE 3: Please refer to the Phase Noise Plot.

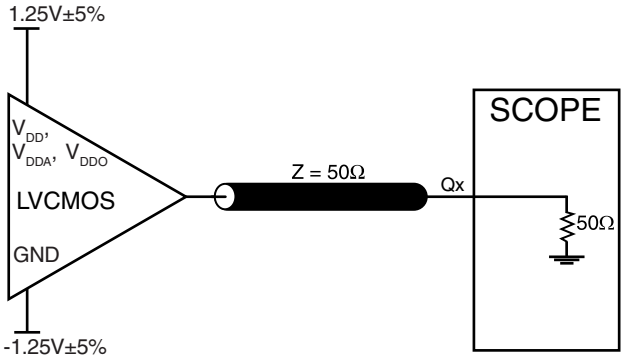
PARAMETER MEASUREMENT INFORMATION



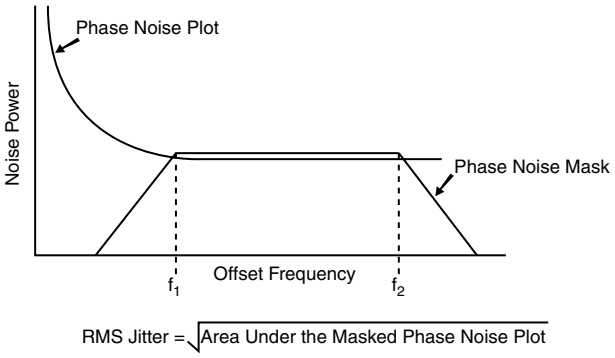
3.3V CORE/3.3V OUTPUT LOAD AC TEST CIRCUIT



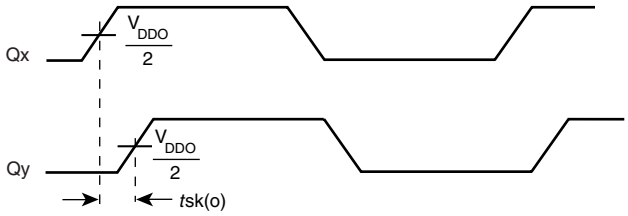
3.3V CORE/2.5V OUTPUT LOAD AC TEST CIRCUIT



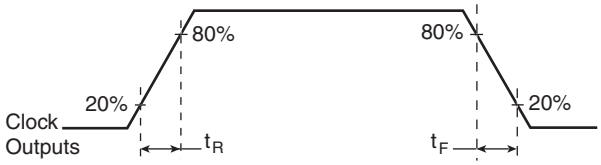
2.5V CORE/2.5V OUTPUT LOAD AC TEST CIRCUIT



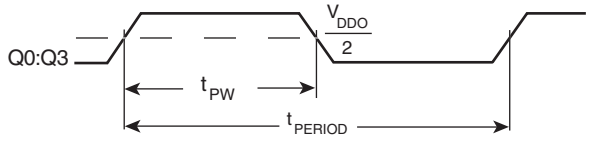
RMS PHASE JITTER



OUTPUT SKEW



OUTPUT RISE/FALL TIME



$$odc = \frac{t_{PW}}{t_{PERIOD}} \times 100\%$$

OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD

APPLICATION INFORMATION

POWER SUPPLY FILTERING TECHNIQUES

As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. The ICS840004I-01 provides separate power supplies to isolate any high switching noise from the outputs to the internal PLL. V_{DD}, V_{DDA}, and V_{DDO} should be individually connected to the power supply plane through vias, and bypass capacitors should be used for each pin. To achieve optimum jitter performance, power supply isolation is required. *Figure 1* illustrates how a 10Ω resistor along with a 10µF and a .01µF bypass capacitor should be connected to each V_{DDA}.

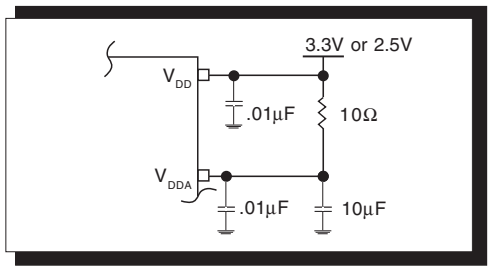


FIGURE 1. POWER SUPPLY FILTERING

CRYSTAL INPUT INTERFACE

The ICS840004I-01 has been characterized with 18pF parallel resonant crystals. The capacitor values shown in *Figure 2* below were determined using a 25MHz 18pF parallel resonant crystal and were chosen to minimize the ppm error.

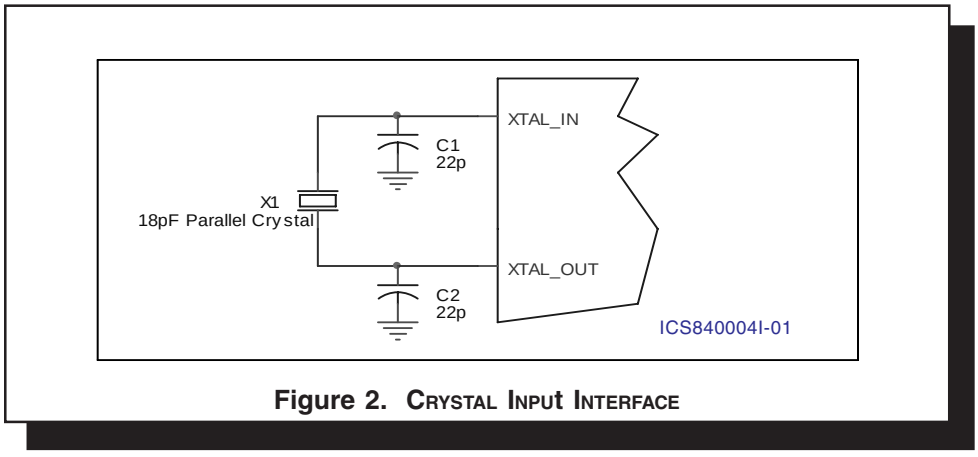


Figure 2. CRYSTAL INPUT INTERFACE

LAYOUT GUIDELINE

Figure 3 shows a schematic example of the ICS840004I-01. An example of LVCMOS termination is shown in this schematic. Additional LVCMOS termination approaches are shown in the LVCMOS Termination Application Note. In this example, an 18pF parallel resonant 25MHz crystal is used. The C1=22pF and C2=22pF are recommended for frequency accuracy. For different board layout, the C1 and C2 may be slightly adjusted for optimizing frequency accuracy. 1KΩ pullup or pulldown resistors can be used for the logic control input pins.

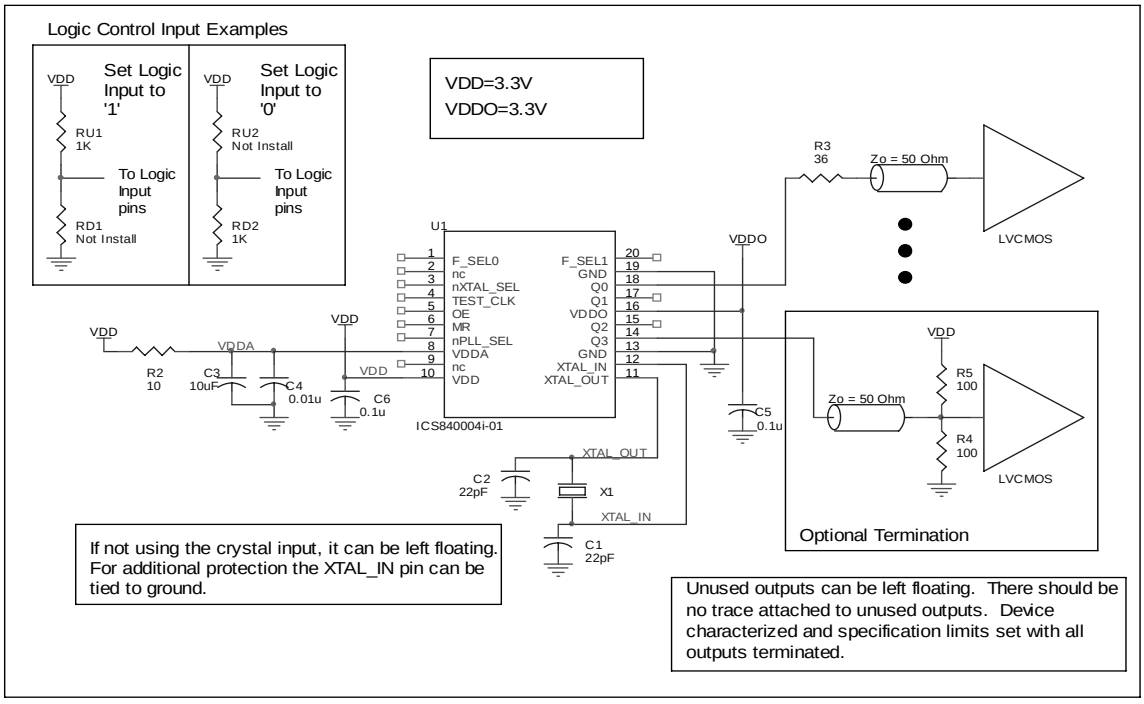


FIGURE 3. ICS840004I-01 SCHEMATIC EXAMPLE

RELIABILITY INFORMATION

TABLE 6. θ_{JA} VS. AIR FLOW TABLE FOR 20 LEAD TSSOP

θ_{JA} by Velocity (Linear Feet per Minute)	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	114.5°C/W	98.0°C/W	88.0°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	73.2°C/W	66.6°C/W	63.5°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

TRANSISTOR COUNT

The transistor count for ICS840004I-01 is: TBD

PACKAGE OUTLINE - G SUFFIX FOR 20 LEAD TSSOP

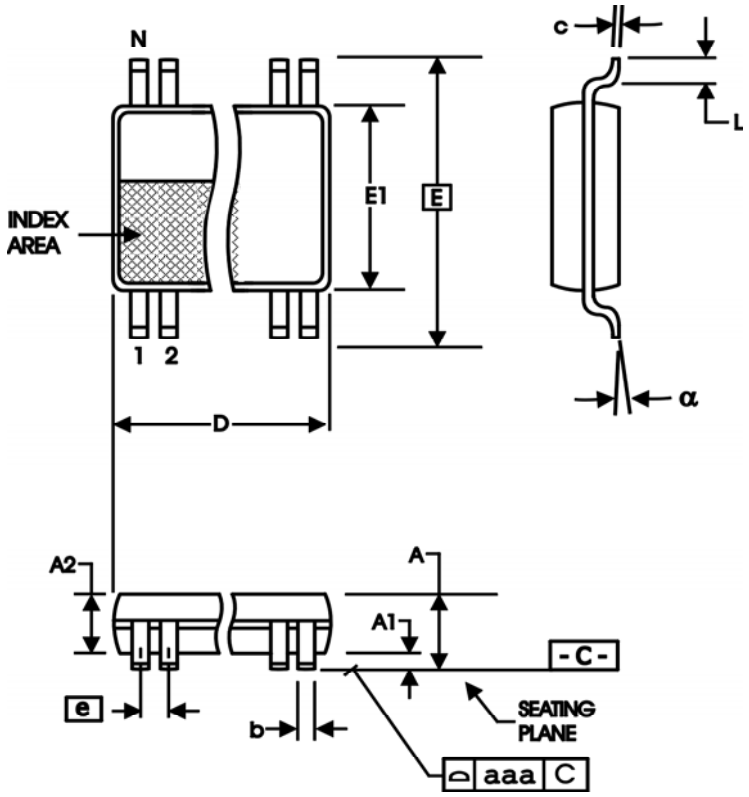


TABLE 7. PACKAGE DIMENSIONS

SYMBOL	Millimeters	
	MIN	MAX
N	20	
A	--	1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	6.40	6.60
E	6.40 BASIC	
E1	4.30	4.50
e	0.65 BASIC	
L	0.45	0.75
α	0°	8°
aaa	--	0.10

Reference Document: JEDEC Publication 95, MO-153

TABLE 8. ORDERING INFORMATION

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
ICS840004AGI-01	ICS840004AI01	20 Lead TSSOP	tube	-40°C to 85°C
ICS840004AGI-01T	ICS840004AI01	20 Lead TSSOP	2500 tape & reel	-40°C to 85°C